SBSA Publications (2009-Present) Journal Articles

1. C. S. Smith, Y. Feng, and S. L. Burkett, “Method For Patterning Poly(Acrylic Acid) Sacrificial Layers For Use In Solder-Based Self-Assembly,” *J. Vac. Sci. Technol. B*, Vol. 35, No. 3, 2017.
2. Y. Feng, C. Smith, S. Burkett, “Process for Patterning Features in Poly(acrylic acid) for Microelectronic Applications,” *J. Micromech. Microeng*., Vol. 27, No. 5, 2017*.*
3. M. Rao, J. C. Lusth, and S. L. Burkett, “A Solder-Based Self Assembly Project in an Introductory IC Fabrication Course,” *American J. Eng. Education*, Vol. 6, No. 1, pp. 11-26, June 2015.
4. M. Rao, J. C. Lusth, and S. L. Burkett, “A Demonstration of Electrical Connectivity between Self Assembled Structures,” *J. Vac. Sci. Technol. B*, Vol. 31, No. 3, pp. 032002-1-032002-11, May/June 2013.
5. M. Rao, J. C. Lusth, and S. L. Burkett, “A Study of Solder Bridging for the Purpose of Assembling Three Dimensional Structures,” *J. Vac. Sci. Technol. B*, Vol. 30, No. 3, pp. 032001-1-032001-12, May/June 2012.
6. M. Rao, J. C. Lusth, and S. L. Burkett, “Analysis of a Dip-Solder Process for Self Assembly,” *J. Vac. Sci. Technol. B*, Vol. 29, No. 4, pp. 042003-1-042003-9, 2011.
7. M. Rao, J. Lusth, and S. L. Burkett, “Self assembly Solder Process to form 3D structures on Silicon,” *J. Vac. Sci. Technol. B*, Vol. 27, No. 1, pp. 76-80, Jan/Feb 2009.

Conference Papers (\*presenting author)

1. M. Rao,\* J. C. Lusth, and S. L. Burkett, “Towards the formation of 3D micro- structured antennas using a solder self assembly process,” *UA GSA conference*, 2009.